IC398 Series (Open Top) Chip Scale Package - SMT (CSP, 0.50mm Pitch)

Specifications

Insulation Resistance:	1,000MΩ min. at 100V DC
Dielectric Withstanding Voltage:	100V AC for 1 minute
Contact Resistance:	100mΩ max. at 10mA/20mV max.
Operating Temperature Range:	–40°C to +150°C
Contact Force:	58.8mN (6gf) per pin approx.
Actuation Force:	19.6N (2kg) max.

Part Number (Details)

Please Contact Yamaichi

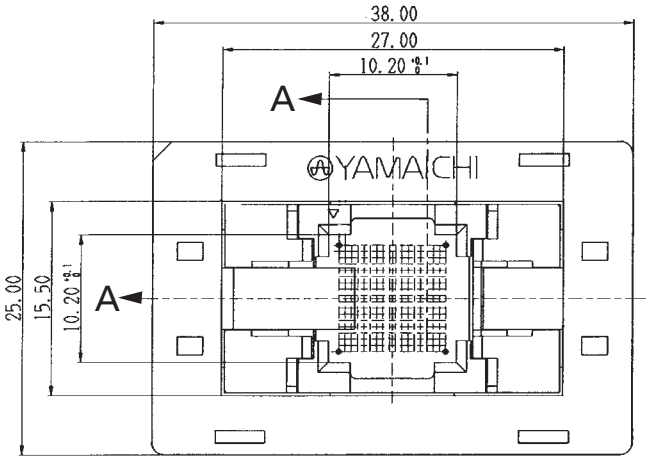
Materials and Finish

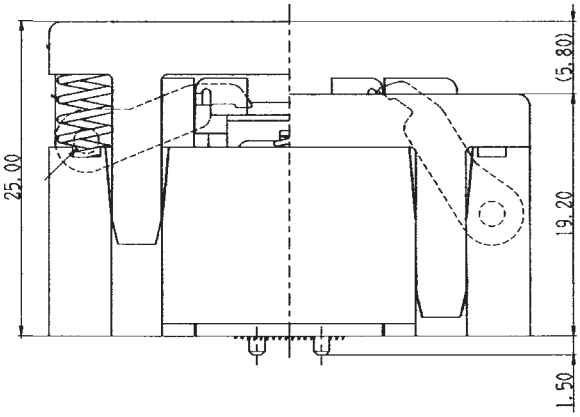
Housing: Polyetherimide (PEI), glass-filled
Polyetherssulphone (PES), glass-filled
Contacts: Beryllium Copper (BeCu)
Plating: Gold over Nickel

Features

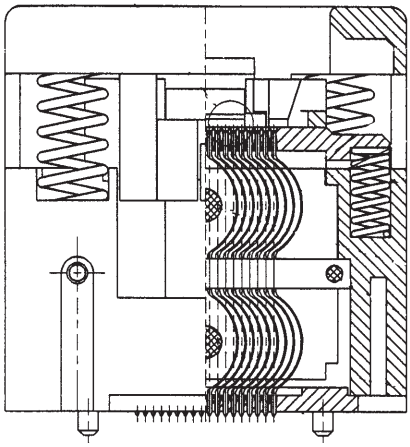
- Open top socket for BGA / LGA / CSP packages with 0.50mm pitch
- SMT soldering (0.50mm pitch)
- 22 x 22 maximum grid size and 12 x12 maximum body size
- Depopulation versions available

Example Socket Dimensions



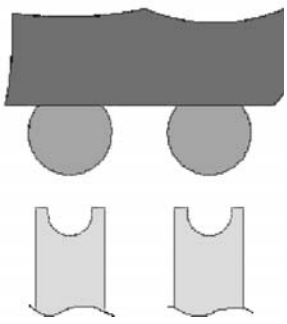


Contact Details

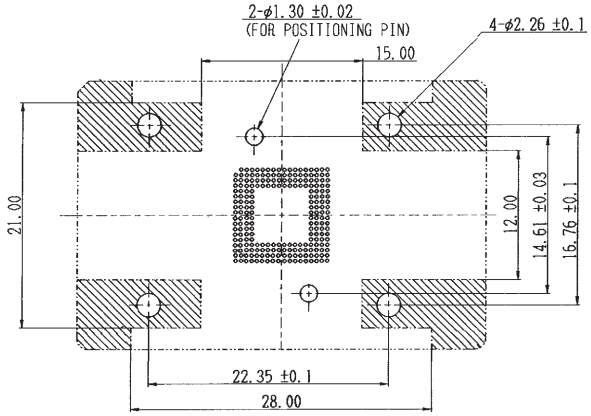


(Section A - A)

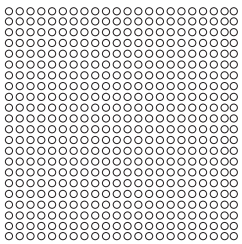
U-shape Contact



Recommended PCB Layout



Typical IC Grid Size 22x22



SPECIFICATIONS ARE SUBJECT TO ALTERATION WITHOUT PRIOR NOTICE – DIMENSIONS IN MILLIMETER

IC398 Series (Open Top) Chip Scale Package - TH (CSP, 0.50mm Pitch)

Specifications

Insulation Resistance:	1,000MΩ min. at 100V DC
Dielectric Withstanding Voltage:	100V AC for 1 minute
Contact Resistance:	100mΩ max. at 10mA/20mV max.
Operating Temperature Range:	–40°C to +150°C
Contact Force:	58.8mN (9gf) per pin approx.
Actuation Force:	39.2N (4kg) max.

Part Number (Details)

Please Contact Yamaichi

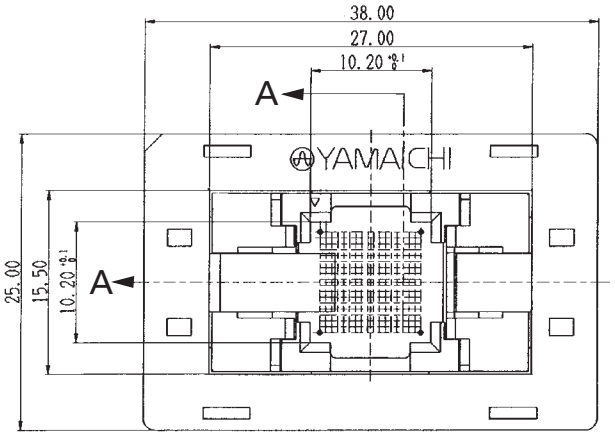
Materials and Finish

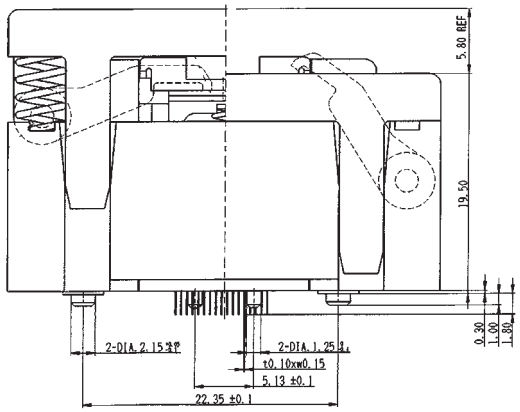
Housing: Polyetherimide (PEI), glass-filled
Polyetherssulphone (PES), glass-filled
Contacts: Beryllium Copper (BeCu)
Plating: Gold over Nickel

Features

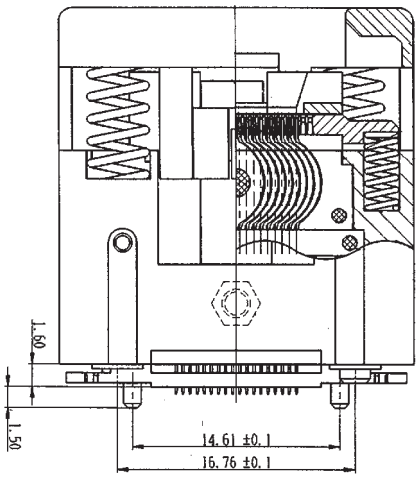
- Open top socket for BGA / LGA / CSP packages with 0.50mm pitch
- Through hole
- 22 x 22 maximum grid size and 12 x12 maximum grid
- Depopulation versions available

Example Socket Dimensions



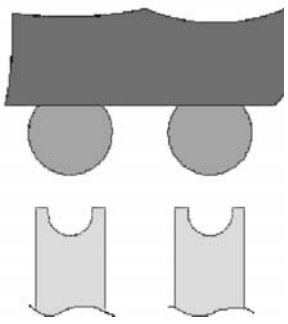


Contact Details

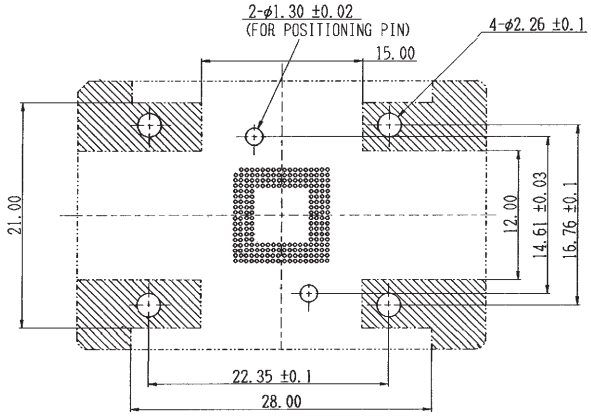


(Section A - A)

U-shape Contact



Recommended PCB Layout



Typical IC Grid Size 22x22